PCT International Publication WO 99/25019 describes a special mixture for mounting and disassembling a semiconductor wafer. German Patent Reference DE 43 32 488 discloses a foil attached as flat as possible by adhesive force. Also known are reversible adhesive layers. It has become apparent, that despite expensive preparation of the wafer substrate, there is an inherent disadvantage in the system. Through the introduction of a protective layer between the active side of the wafer and the assembly carrier, air pockets occur which cause unevenness on the rear side of the wafer. These air pockets can scarcely be eliminated by increasing the compressive force or distributing the local pressure locations. Repeating the pressing process several times also does not achieve the desired result. Moreover, the danger of breaking the wafer is increased in an uncontrolled manner by such manipulations.

REMARKS

Applicant respectfully requests entry of the above Preliminary Amendment to correct a typographical error in the identification of the PCT Reference WO 99/25019, and place this patent application in better form for examination and prosecution before the U.S. Patent and Trademark Office.

Applicant sincerely believes that this patent application is now in condition for examination and prosecution before the U.S. Patent and Trademark Office.

Respectfully submitted,

Douglas H. Pauley
Regis. No. 33,295

Pauley Petersen Kinne & Fejer
2800 West Higgins Road
Suite 365
Hoffman Estates, Illinois 60195
(847) 490-1400
FAX (847) 490-1403

Marked-up Version Showing Changes Made

In the Specification:

Page 3, lines 1-11

PCT International Publication [WO 092479] WO 99/25019 describes a special mixture for mounting and disassembling a semiconductor wafer. German Patent Reference DE 43 32 488 discloses a foil attached as flat as possible by adhesive force. Also known are reversible adhesive layers. It has become apparent, that despite expensive preparation of the wafer substrate, there is an inherent disadvantage in the system. Through the introduction of a protective layer between the active side of the wafer and the assembly carrier, air pockets occur which cause unevenness on the rear side of the wafer. These air pockets can scarcely be eliminated by increasing the compressive force or distributing the local pressure locations. Repeating the pressing process several times also does not achieve the desired result. Moreover, the danger of breaking the wafer is increased in an uncontrolled manner by such manipulations.